

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6321955

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TORU HAYASHIDA	09/18/2020
SHUNSAKU YOSHIKAWA	09/18/2020
TAKASHI SAITO	09/18/2020
KANTA DEI	09/18/2020
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23, SENJU-HASHIDO-CHO
City:	ADACHI-KU, TOKYO
State/Country:	JAPAN
Postal Code:	120-8555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17042551
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	434620-000273
NAME OF SUBMITTER:	JEFFREY L. COSTELLIA
SIGNATURE:	/jeffrey L. costellia/
DATE SIGNED:	09/28/2020
Total Attachments: 3	
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P2932

OSP 05421 (OS)

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1/3

Docket No. _____

ASSIGNMENT

WHEREAS, (I/we), (1) Toru HAYASHIDA; (2) Shunsaku YOSHIKAWA; (3) Takashi SAITO; and (4) Kanta DEI a citizen of Japan, residing at (1) Tokyo, Japan, (2) Tokyo, Japan, (3) Tokyo, Japan, and (4) Tokyo, Japan, have invented a SOLDER PASTE

for which (I/we) have executed application papers for U.S. patent application filed herewith; and

WHEREAS, SENJU METAL INDUSTRY CO., LTD. having a place of business located at 23, Senju-hashido-cho, Adachi-ku, Tokyo 120-8555 Japan, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, (I/we), (1) Toru HAYASHIDA; (2) Shunsaku YOSHIKAWA; (3) Takashi SAITO; and (4) Kanta DEI, do sell, assign, transfer and set over unto the said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, in accordance with this Assignment.

P2932
05P85421(US)
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Docket No. _____

[ASSIGNMENT CONTINUATION]

Re: U.S. Patent Application entitled: SOLDER PASTE

Inventor: Toru HAYASHIDA

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

18th day of September, 2020.
(date) (month) (year)

Toru Hayashida
Name: Toru HAYASHIDA

Re: U.S. Patent Application entitled:

Inventor: Shunsaku YOSHIKAWA

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

18th day of September, 2020.
(date) (month) (year)

Shunsaku Yoshikawa
Name: Shunsaku YOSHIKAWA

P2932

OSP-85421(05)

譲 3/3

Docket No. _____

[ASSIGNMENT CONTINUATION]

Re: U.S. Patent Application entitled: SOLDER PASTE

Inventor: Takashi SAITO

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

18th day of September, 2020.
(date) (month) (year)

Takashi Saito

Name: Takashi SAITO

Re: U.S. Patent Application entitled:

Inventor: Kanta DEI

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

18th day of September, 2020.
(date) (month) (year)

Kanta Dei

Name: Kanta DEI